



N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

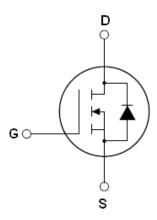
Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS}	650	V
R _{DS(ON)TYP}	220	mΩ
I_D	15	A



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65T260K	TO-252	NCE65T260K
NCE65T260I	TO-251	NCE65T260I





TO-252

TO-251

Table 1. Absolute Maximum Ratings ($T_c=25^{\circ}C$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	V _{GS}	±30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	15	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	10	Α
Pulsed drain current (Note 1)	I _{DM (pluse)}	60	Α
Maximum Power Dissipation(Tc=25℃)	P _D	131	W
Derate above 25°C		1.05	w/°C
Single pulse avalanche energy (Note 2)	Eas	304	mJ
Avalanche current ^(Note 1)	I _{AR}	3	Α
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	1.6	mJ



v1.0

Parameter	Symbol	Value	Unit
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V}, I_{SD} < I_{D}$	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55+150	°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	0.95	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25 ℃ unless otherwise noted)

Table 3. Liectifical Characteristics	Stics (TA-23 Cuttless otherwise noted)					
Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250μA	3	3.5	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =8A		220	260	mΩ
Dynamic Characteristics						
Input Capacitance	C _{lss}	\/ F0\/\\ 0\/		1210	1400	pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V,		74		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		0.2		pF
Total Gate Charge	Qg	1/ 400)// 454		24.7	42	nC
Gate-Source Charge	Q_{gs}	V _{DS} =480V,I _D =15A,		8.2		nC
Gate-Drain Charge	Q_{gd}	- V _{GS} =10V		8.5		nC
Switching times	•		•	•		
Turn-on Delay Time	t _{d(on)}			14		nS
Turn-on Rise Time	t _r	V_{DD} =380V, I_{D} =8A,		8		nS
Turn-Off Delay Time	$t_{d(off)}$	$R_G=2.3\Omega, V_{GS}=10V$		55		nS
Turn-Off Fall Time	t _f			7		nS
Source- Drain Diode Characteristics	•		•	•		
Source-drain current(Body Diode)	I _{SD}	T 0500			15	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			60	Α
Forward On Voltage	V_{SD}	Tj=25°C,I _{SD} =15A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}			240		nS
Reverse Recovery Charge	Q _{rr}	Tj=25°C,I _F =7.5A,di/dt=100A/μs		2		uC
Peak Reverse Recovery Current	I _{rrm}	1		17		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

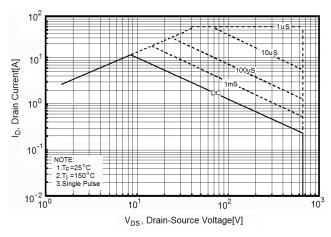


Figure 3. Source-Drain Diode Forward Voltage

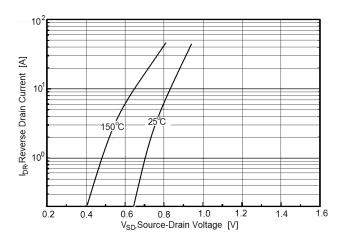


Figure 5. Transfer characteristics

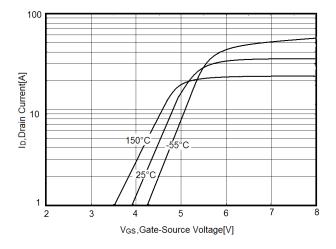


Figure 2. Transient Thermal Impedance

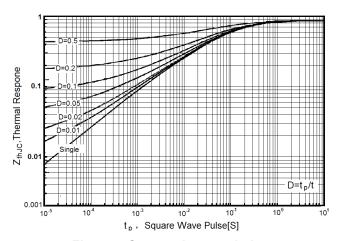


Figure 4. Output characteristics

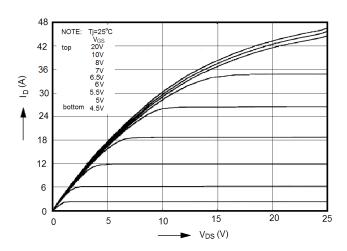
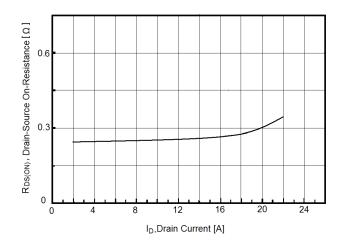


Figure 6. Static drain-source on resistance



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Figure 7. R_{DS(ON)} vs Junction Temperature

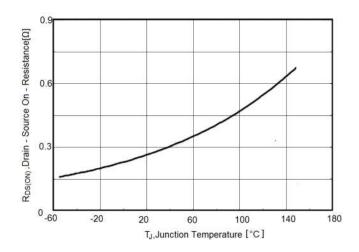


Figure8. BV_{DSS} vs Junction Temperature

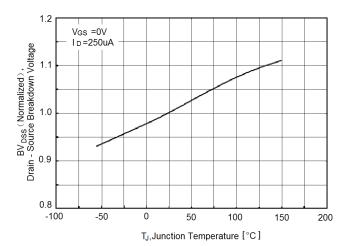


Figure 9. Maximum I_{D} vs Junction Temperature

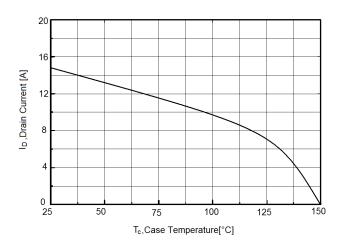


Figure 10. Gate charge waveforms

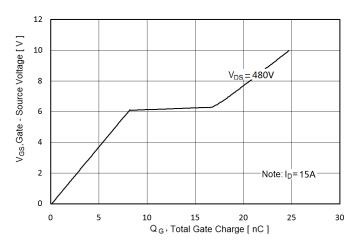
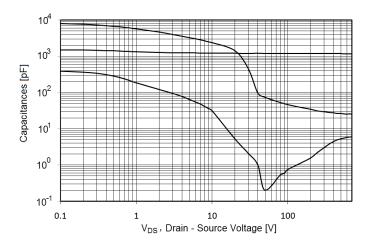


Figure 11. Capacitance

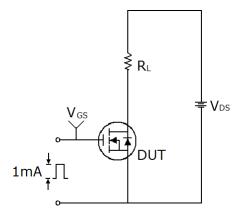


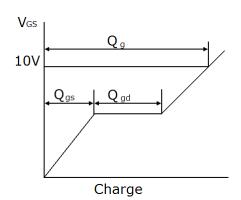




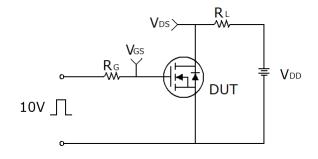
Test circuit

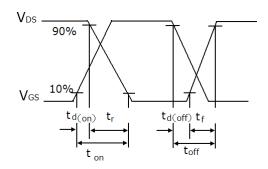
1) Gate charge test circuit & Waveform



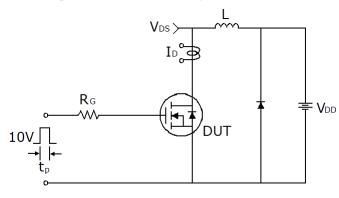


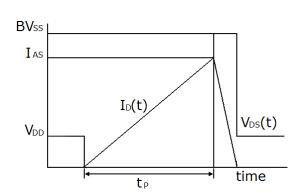
2) Switch Time Test Circuit:





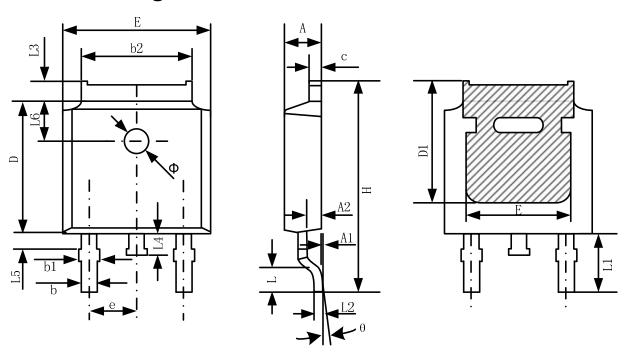
3) Unclamped Inductive Switching Test Circuit & Waveforms







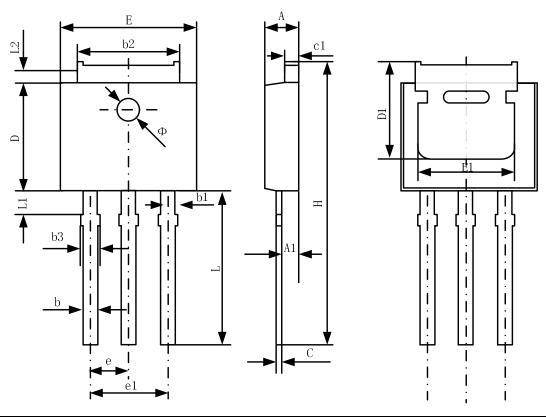
TO-252-2 Package Information



Compleal	Dimension	s In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.20	2.38	0.087	0.094	
A1	0.00	0.10	0.000	0.004	
A2	0.90	1.10	0.035	0.043	
b	0.72	0.85	0.028	0.033	
b1	0.72	0.90	0.028	0.035	
b2	5.13	5.46	0.202	0.215	
С	0.47	0.60	0.019	0.024	
D	6.00	6.20	0.236	0.244	
D1	5.25		0.207		
Е	6.50	6.70	0.256	0.264	
E1	4.70		0.185		
e	2.19	2.39	0.086	0.094	
Н	9.80	10.40	0.386	0.409	
L	1.40	1.70	0.055	0.067	
L1	2.9	00 REF	0.114 REF		
L2	0.5	08 BSC	0.020 BSC		
L3	0.90	1.25	0.035	0.049	
L4	0.60	1.00	0.024	0.039	
L5	0.15	0.75	0.006	0.030	
L6	1.80 REF		0.071 REF		
Ф	1.20	1.40	0.047	0.055	
θ	0°	8°	0°	8°	



TO-251 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	2.20	2.35	0.087	0.093	
A1	0.90	1.10	0.035	0.043	
b	0.56	0.69	0.022	0.027	
b1	0.77	0.90	0.030	0.035	
b2	5.23	5.43	0.206	0.214	
b3		1.05	0.000	0.041	
С	0.46	0.59	0.018	0.023	
c1	0.46	0.59	0.018	0.023	
D	6.00	6.20	0.236	0.244	
D1	5.20		0.205		
Е	6.50	6.70	0.256	0.264	
E1	4.60	5.00	0.181		
e	2.24	2.34	0.088	0.092	
e1	4.47	4.67	0.176	0.184	
Н	16.18	16.78	0.637	0.661	
L	9.00	9.60	0.354	0.378	
L1	0.95	1.35	0.037	0.053	
L2	0.90	1.25	0.035	0.049	



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